IN THE CLAIMS:

Please amend the claims as follows:

1. (original) A package for a micro-electromechanical device (MEMS package), comprising:

an inner enclosure having an inner cavity defined therein; and

a fill port channel communicating with said inner cavity and of sufficient length to allow a quantity of adhesive to enter said fill port channel while preventing said adhesive from entering said inner cavity.

2. (original) The MEMS package of claim 1, wherein said fill port channel extends at least partially into said inner enclosure.

3. (currently amended) The MEMS package of ~~claim 2~~ claim 1, further comprising a flow control structure extending at least partially into said ~~inner enclosure~~ fill port channel and wherein said flow control structure prevents said adhesive from entering said cavity by physically obstructing a portion of ~~separating~~ said fill port channel ~~from said inner cavity~~.

4. (original) The MEMS package of claim 3, further comprising locking features formed on said flow control structure, wherein said locking features cause said fill port channel to have a variable cross section.

5. (original) The MEMS package of claim 4, wherein said locking features comprise tapered sections formed on said flow control structure to form a choke point in said fill port channel.

6. (withdrawn) The MEMS package of claim 4, wherein said locking features comprise stepped sections to form a choke point in said fill port channel.

7. (original) The MEMS package of claim 3, wherein said flow control structure comprises a peninsula.

8. (withdrawn) The MEMS package of claim 1, wherein said fill port channel is external to said inner enclosure.

9. (withdrawn) The MEMS package of claim 8, further comprising a locking feature disposed within said fill port channel creating a variable cross section in said fill port channel.

10. (withdrawn) The MEMS package of claim 9, wherein said locking feature comprises an island in said fill port channel.

11. (withdrawn) The MEMS package of claim 9, wherein said locking feature comprises a plurality of islands in said fill port channel.

12. (withdrawn) The MEMS package of claim 8, wherein said fill port channel follows a tortuous path.

13. (withdrawn) The MEMS package of claim 12, wherein said tortuous path comprises a serpentine path.

14. (withdrawn) The MEMS package of claim 1, wherein said fill port channel is external to said inner cavity and further comprising a plurality of locking feature groups disposed within said fill port channel, wherein said locking feature groups comprise varying sizes of locking features configured to prevent contaminants from reaching said inner cavity.

15. (withdrawn) The MEMS package of claim 14, wherein locking feature groups comprise a first locking feature group having locking features of a first size, a second feature group having locking features of a second size being smaller than said first size, and a third locking feature group having a locking features of a third size being smaller than said second size.

16. (withdrawn) The MEMS package of claim 15, wherein said locking features comprise island locking features.

17-23. (cancelled)

24. (original) A package for a micro-electromechanical device (MEMS device), comprising:

an inner enclosure having an inner cavity defined therein;

a fill port channel coupling said inner cavity to an atmosphere; and

flow control structure extending at least partially into said inner enclosure and being configured to control the flow of fluid into said inner cavity.

25. (original) The MEMS package of claim 24, wherein said flow control structure comprises a physical barrier between said fill port channel and a portion of said inner cavity.

26. (original) The MEMS package of claim 25, wherein said physical barrier comprises a peninsula.

27. (original) The MEMS package of claim 24, further comprising locking features formed on said flow control structure.

28. (original) The MEMS package of claim 27, wherein said locking features comprise tapered sections formed on said flow control structure.

29. (original) The MEMS package of claim 28, wherein said tapered sections form a choke point at an intermediate portion of said fill port channel.

30. (withdrawn) The MEMS package of claim 27, wherein said locking features comprise a plurality of stepped portions.

31. (withdrawn) The MEMS package of claim 30, wherein said stepped portions form a choke point at an intermediate portion of said fill port channel.

32. (currently amended) A micro-electromechanical (MEMS) assembly, comprising:

a MEMS device disposed at least partially within a package[[,]];

~~wherein~~ said package ~~includes~~ including an inner enclosure having an inner cavity defined therein, and a fill port channel coupling said inner cavity to an atmosphere and physically separating said atmosphere and said inner cavity by a distance sufficient to allow a variable flow of adhesive to enter said fill port channel while preventing said adhesive from entering said inner cavity; [[and]]

an adhesive seal coupled to said fill port channel; and

a diaphragm disposed in said inner cavity for changing a volume of said inner cavity so as to draw a quantity of said adhesive seal through said fill port channel.

33. (original) The assembly of claim 32, further comprising a fluid contained within said inner cavity.

34. (currently amended) The assembly of ~~claim 32~~ claim 33, wherein said fluid comprises a degassed packaging fluid.

35. (original) The assembly of claim 32, wherein said adhesive is physically separated from said MEMS device by said flow control structure.

36. (original) The assembly of claim 32, and further comprising locking features formed in said fill port channel and wherein said adhesive seal is locked in said fill port channel by said locking features.

37. (original) The assembly of claim 32, wherein said adhesive seal comprises a photo resist material.

38. (original) The assembly of claim 32, wherein said adhesive seal comprises a solder material.

39. (original) The assembly of claim 32, wherein said adhesive comprises a thermo-set material.

40. (original) The assembly of claim 32, wherein said adhesive comprises UV curable epoxy.

41. (original) The assembly of claim 32, wherein said adhesive comprises thermoset epoxy.

42. (original) The assembly of claim 32, wherein said adhesive comprises moisture/fluid cure adhesive.

43. (currently amended) A method of forming a package for a micro-electromechanical device (MEMS device), comprising:

forming an inner enclosure having an inner cavity defined therein; [[and]]

forming a fill port channel, wherein said fill port channel is in fluid communication with an atmosphere and said inner cavity and is of sufficient length to allow a variable flow of adhesive to enter said fill port channel while preventing said adhesive from entering said inner cavity; and

flowing a quantity of said adhesive through a fill port of said fill port channel and into said fill port channel.

44. (original) The method of claim 43, wherein said fill port channel extends at least partially into said inner enclosure and further comprising forming a flow control structure to form said fill port channel and to physically separate said fill port channel from said inner cavity.

45. (original) The method of claim 44, wherein said flow control structure further comprises locking features formed thereon.

46. (original) The method of claim 45, wherein said locking features form at least one choke point at an intermediate portion of said fill port channel.

47. (original) The method of claim 45, wherein said locking features comprise a plurality of tapered sections which form a choke point at an intermediate portion of said fill port channel.

48. (withdrawn) The method of claim 45, wherein said locking features comprise a plurality of stepped sections that form a choke point at an intermediate portion of said fill port channel.

49. (withdrawn) The method of claim 44, wherein said fill port channel is external to said inner enclosure and further comprising forming an island flow control structure within said fill port channel.

50. (withdrawn) The method of claim 44, wherein said fill port channel follows a curvaceous path.

51-53. (cancelled)

54. (currently amended) A micro-electromechanical system (MEMS) package, comprising:

means for containing a MEMS device;

a fluid with said MEMS device in said means for containing said MEMS device;

means for introducing [[a]] said fluid into an interior cavity of said means for containing said MEMS device;

an adhesive flowed into said means for introducing said fluid; and

means for controlling a flow of said adhesive through said means for introducing said fluid to as to prevent said adhesive from entering said interior cavity ~~separating a portion of said means for containing said MEMS device from said means for introducing said fluid~~.

55. (currently amended) The package of claim 54, further comprising means for locking [[an]] said adhesive within said means for introducing said fluid.

56. (withdrawn) The package of claim 55, wherein said means for locking said adhesive includes means for filtering said fluid.

57. (new) The MEMS package of claim 1, further comprising a fluid filling said inner enclosure.

58. (new) The MEMS package of claim 57, further comprising an airless interface between said fluid and said adhesive in said fill port channel.

59. (new) The MEMS package of claim 57, further comprising at least one diaphragm disposed in said inner cavity for changing a volume of said inner cavity so as to draw a quantity of said adhesive through said fill port channel.

60. (new) The MEMS package of claim 24, further comprising a fluid filling said inner enclosure.

61. (new) The MEMS package of claim 60, further comprising:

an adhesive in said fill port channel to seal said channel; and

an airless interface between said fluid and said adhesive in said fill port channel.

62. (new) The MEMS package of claim 61, further comprising at least one diaphragm disposed in said inner cavity for changing a volume of said inner cavity so as to draw a quantity of said adhesive through said fill port channel.